

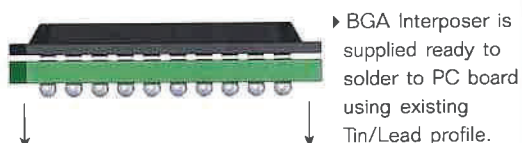
Lead-free to Tin/Lead BGA Interposer

www.advanced.com

New BGA Interposers from Advanced Interconnections are a cost-effective method for converting lead-free BGA device packages for use on boards processed with lower temperature, Tin/Lead solder profiles.

Designed for RoHS exempt applications, Interposers from Advanced solve BGA device transition, obsolescence, and solderability issues associated with the higher temperatures required to process lead-free BGA packages.

How It Works



PC BOARD

► Advanced's production-ready solution consists of lead-free BGA device attach service to custom Interposer adapter boards in a high temperature reflow process, followed by mounting of eutectic (63Sn/37Pb) solder balls on the bottom of the Interposers.*

► Submit device package mechanical specifications along with quantity requirements for quotation.

*BGA devices can be supplied by customer or sourced by Advanced.

Features

- The compact Interposer assembly is shipped ready for use on existing PC boards, eliminating the need to change Tin/Lead solder profiles or subject other components to higher processing temperatures
- High temperature, FR-4 adapter boards closely match the original package size
- Industry-proven eutectic (63/37) Tin/Lead solder balls offer the superior reliability and processing results of original Tin/Lead BGA device packages
- In-house (high temperature) lead-free BGA device attach
- Interposers match the BGA device footprint (currently available in 0.80, 1.00, and 1.27mm pitch)
- Standard tray packaging or Tape & Reel available upon request

TYPICAL APPLICATIONS

- Medical, military and other RoHS exempt products
- PC boards with heat-sensitive components
- Tin/Lead BGA device package transition and obsolescence



ADVANCED
INTERCONNECTIONS.

5 Energy Way, West Warwick, Rhode Island 02893 USA
Tel: 800.424.9850 | 401.823.5200 | Fax: 401.823.8723
E-mail: info@advanced.com | Web: www.advanced.com